Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment





ATS Part#: ATS-51230D-C1-R0

Description: maxiFLOWTM maxiGRIPTM HS Assembly- LP, T766, BLACK- ANODIZED

Heat Sink Type: maxiFLOW
Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-51230D-C2-R0 Discontinued

*Image above is for illustration purpose only.

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- · Comes pre-assembled with high performance, phase changing, thermal interface material
- Designed for low profile components from 1.5 to 2.99mm
- "Keep-Out" Requirements: An "Un-Populated" border zone of 5mm around the component is necessary to facilitate the Installation/Removal of the maxiGRIP™. Please refer to the maxiGRIP™ Keep-Out Guidelines and maxiGRIP™ Installation/Removal Instructions for further details.

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	10.99 °C/W	8.88 °C/W	7.67 °C/W	6.87 °C/W	6.27 °C/W	5.81 °C/W	5.45 °C/W
	Ducted Flow	7.51	n/a	n/a	n/a	n/a	n/a	n/a

Product Detail



For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

